03-03-2004

U.S. DEPARTMENT OF COMMERCE

(Rev. 03/ 01) OMB No. 0651-0027 (exp. 5/31/2002) PATENTS	ONLY	
To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof		
Name of conveying party(ies):	Name and address of receiving party(ies)	
1. Kazuyuki YAMAMOTO (2/19/04) 5. Toshio Mamiya	Name: Sony Corporation	
2. Takashi YAMADA (2/20/04) (2/23/04) 3. Masami MIIKE (2/20/04)	Internal Address:	
4. Kazutoshi YAMAMOTO (2/23/04)	Street Address:	
Additional name(s) of conveying party(ies) attached? Yes x No	6-7-35 Kitashinagawa Shinagawa-Ku	
3. Nature of Conveyance:		
x Assignment Merger		
Security Agreement Change of Name	City: Tokyo	
Other	Country: Japan Zip: 141-0001	
Execution Date: See conveying parties above	Additional name(s) & Yes x No address(es) attached:	
4. Application number(s) or patent number(s):		
If this document is being filed together with a new application, the exe	ecution date of the new application is:	
A. Patent Application No.(s): 10/684,459	B. Patent No.(s):	
Additional numbers attache	ed? Yes x No	
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:1	
Name: Ronald P. Kananen	7. Total fee (37 CFR 3.41) \$ 40.00	
RADER, FISHMAN & GRAUER PLLC		
Charat Adduses	Enclosed	
Street Address: 1233 20th Street, N.W., Suite 501	x Authorized to be charged to deposit account	
	Authorized to be charged to credit card (Form 2038 enclosed)	
	8. Deposit account number:	
City: State: Zip:	18-0013	
Washington DC 20036	(Attach duplicate copy of this page if paying by deposit account)	
DO NOT USE THIS SPACE		
9. Statement and signature.		
To the best of my knowledge and belief, the foregoing info	rmation is true and correct and any attached copy	
is a true copy of the original document.		
Ronald P. Kananen Name of Person Signing	February 27, 2004 Signature Date	

DC142192

03/02/2004 ECDOPER 00000062 180013 10684459

Docket Number:	SON-2835
Docket Hamber.	

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in HEAD ACTUATOR, HARD DISK APPARATUS AND METHOD OF MANUFACTURING A HEAD ACTUATOR for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address: AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention. said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries; NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration. the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto; And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto; And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense; And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto; And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale. And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 10/684,459 Filing Date: October 15, 2003 This assignment executed on the dates indicated below. Kazuyuki YAMAMOTO Name of first or sole inventor Execution date of U.S. Patent Application Kanagawa, Japan Residence of first or sole inventor

Kazuyaki Damametu Signature of first or sole inventor

PATENT REEL: 015016 FRAME: 0424

February 19, 2004

Takashi YAMADA	
Name of second inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of second inventor Japan Li Jamade	Feb. 20, 2004
Signature of second inventor	Date of this assignment
Masami MIIKE	
Name of third inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of third inventor Mascumi Miki	Hebray 20.204 Date of this assignment
Signature of third inventor	Date of this assignment
Kazutoshi YAMAMOTO	
Name of fourth inventor	Execution date of U.S. Patent Application
Tokyo, Japan	**
Residence of fourth inventor	
Kazutoshi Gamamoto	Feb. 23, 2004
Signature of fourth inventor	Date of this assignment
Toshio MAMIYA	
Name of fifth inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of fifth inventor	
Joshio Mamiya	Feb. 23, 2004
Signature of fifth inventor $\mathscr O$	Date of this assignment

RECORDED: 02/27/2004

PATENT REEL: 015016 FRAME: 0425